SDS252010D SERIES

1. PART NO. EXPRESSION:

 $\frac{\text{S D S}}{\text{(a)}} \, \frac{\text{2 5 2 0 1 0}}{\text{(b)}} \, \frac{\text{D}}{\text{(c)}} \, \frac{\text{1 0 0}}{\text{(d)}} \, \frac{\text{M}}{\text{(e)}} \frac{\text{F}}{\text{(f)}}$

(a) Series code

(d) Inductance code: 100 = 10.0uH

(b) Dimension code

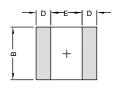
(e) Tolerance code : $M = \pm 20\%$

(c) Material code

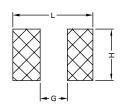
(f) F: RoHS Compliant

2. CONFIGURATION & DIMENSIONS:







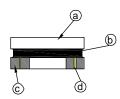


Recommended PCB Pattern

Unit:m/m

А	В	С	D	E	L	G	Н
2.5 -0.1/+0.2	2.0 -0.05/+0.35	1.02 Max.	0.85 Ref.	0.80 Ref.	2.9 Ref.	0.8 Ref.	2.4 Ref.

3. MATERIALS:



(a) Core: Ferrite Core

(b) Coating: Epoxy with magnetic powder

(c) Termination : Tin Pb Free

(d) Wire: Enameled Copper Wire

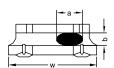
Exposed wire tolerance limit of coating resin part on product side.

Size of exposed wire occurring to coating resin is specified below.

1. Width direction $\,(\,\mbox{dimension}\,\,a)\,:\,\mbox{Acceptable}$ when $a\!\leq\!w\!/2$

Nonconforming when a>w/2

- 2. Length direction (dimension b): Dimension b is not specified.
- The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, and is acceptable.





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4. GENERAL SPECIFICATION:

a) ambient temp. : 25° C

b) Isat : Based on inductance change ($\Delta L/L0$: \leq -30%) c) Irms : Based on temperature rise (ΔT : 40°C) Max

d) Operating temp. : -55° C to 125° C(for products in unopened tape package, less than 40° C)

5. ELECTRICAL CHARACTERISTICS:

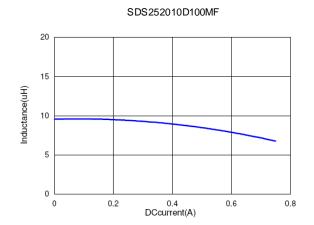
Part No.	Inductance (uH)	Test Frequency (Hz)	DCR (Ω)±20%	Isat (A) Typ.	Irms (A) Typ.
SDS252010D100MF	10± 20%	0.1V/1M	0.47	0.75	0.75
SDS252010D220MF	22± 20%	0.1V/1M	1.120	0.50	0.50

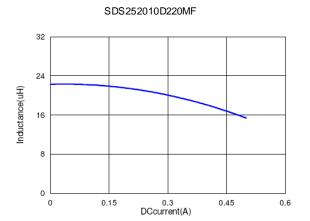


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6. CHARACTERISTICS CURVES:







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7. RELIABILITY AND TEST CONDITION:

ITEM	PERFORMANCE	TEST CONDITION				
Electrical Characteristics T	est					
Inductance L	Refer to standard electrical characteristics list	Agilent-4291, Agilent-4287				
Q		Agilent-4192, Agilent-4285				
SRF		Agilent-4291				
DC Resistance		Agilent-4338				
Rated Current	Base on temp. rise & ΔL/L0A≦30%.	Saturation DC Current (Isat) will cause L0				
		to drop approximately ΔL(%).				
Temperature Rise Test	ΔT 40°CMax	Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT(°C) without core loss. 1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer				
Mechanical Performance T	est					
Solder Heat Resistance	Appearance: No damage. Inductance: within± 10% of initial value Q: Shall not exceed the specification value.	Temperature Time Temperature Number ramp/immersion of heat and emersion rate cycles				
	RDC : within ± 15% of initial value and shall not exceed the specification value	260±5 (solder temp) 10±1 25mm/s±6 mm/s 1				
	exceed the specification value	Depth: completely cover the termination				
Solderability Test	More than 95% of terminal electrode should be covered with solder.	Preheat: 150° C,60sec Solder: Sn99.5%-Cu0.5% Temperature: 245±5° C Flux for lead free: Rosin.9.5% Dip time: 4±1sec Depth: completely cover the termination				
Reliability Test						
Life Test	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	Preconditioning:Run through IR reflow for 2 times.(IPC/ JEDEC J-STD-020DClassification Reflow Profiles Temperature: 85±2° C(Inductor) Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs				
Thermal shock		Preconditioning:Run through IR reflow for 2 times.(IPC/ JEDEC J-STD-020DClassification Reflow Profiles Step1: -40± 2° C 30±5min Step2: 25±2°C ≤ 0.5min Step3: 105± 2° C 30±5min Number of cycles: 500 Measured at room femprature after placing for 24± 2 hrs				
Humidity Resistance Test		Preconditioning:Run through IR reflow for 2 times.(IPC/ JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2% R.H Temperature: 85° C±2° C Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs				
Vibration Test		Preconditioning:Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude: 1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations)				

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8. SOLDERING AND MOUNTING:

8-1. Soldering

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-1.1 Lead Free Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

8-1.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note:

- a) Preheat circuit and products to 150° C.
- b) 355° C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4-5 secs.

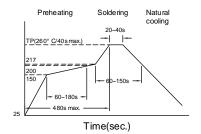


Figure 1. Re-flow Soldering : 3 times max.

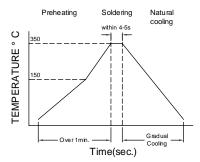


Figure 2. Iron Soldering: 1 times max.

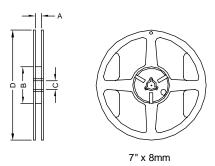


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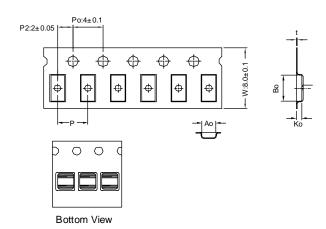
9. PACKAGING INFORMATION:

9-1. Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
7" x 8mm	8.4±1.0	50 Min.	13±0.8	178±2

9-2 Tape Dimension / 8mm



Series	Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	t(mm)
SDS252010D	2.45±0.1	2.85±0.1	1.40±0.1	4.0±0.1	0.23± 0.05

9-3. Packaging Quantity

Size	SDS252010D
Chip / Reel	2000

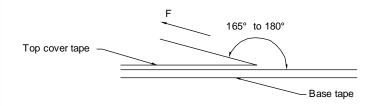


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9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed (mm/min)
(° C)	(%)	(hPa)	
5~35	45~85	860~1060	300

Application Notice

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Temperature and humidity conditions: Less than 40° C and 60% RH.
- b) Recommended products should be used within 12 months from the time of delivery.
- c) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



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